# **Specification of Thermoelectric Module**

## TES1-24154ID69OD86

### Description

The 241 couples,  $\phi = 86$ mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70 °C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant

Hot side:Th

- Precise temperature control
- Exceptionally reliable in quality, high performance

### **Performance Specification Sheet**

### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

| Th (°C)                    | 27    | 50   | Hot side temperature at environment: dry air, N <sub>2</sub> |  |
|----------------------------|-------|--|--|--|
| DT <sub>max</sub> (°C)     | 70    | 79 Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |  |  |
| U <sub>max</sub> (Voltage) | 30.7  | 33.1   | Voltage applied to the module at DT <sub>max</sub>           |  |
| I <sub>max</sub> (Amps)    | 5.4   | 5.4  | DC current through the modules at DT <sub>max</sub>          |  |
| Q <sub>Cmax</sub> (Watts)  | 102.1 | 109.9  | Cooling capacity at cold side of the module under DT=0 °C    |  |
| AC resistance (Ohms)       | 4.4   | 4.7  | The module resistance is tested under AC                     |  |
| Tolerance (%)              | 10%   |  | For thermal and electricity parameters                       |  |

### Geometric Characteristics Dimensions in millimeters

## **Manufacturing Options**

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)

#### B. Sealant:

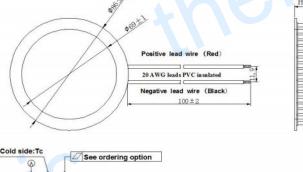
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

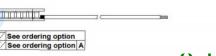
#### C. Ceramics:

- 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
- 2. Aluminum Nitride (AlN)

#### **D.** Ceramics Surface Options:

- 1. Blank ceramics (not metalized)
- 2. Metalized (Au plating)





## **Ordering Option**

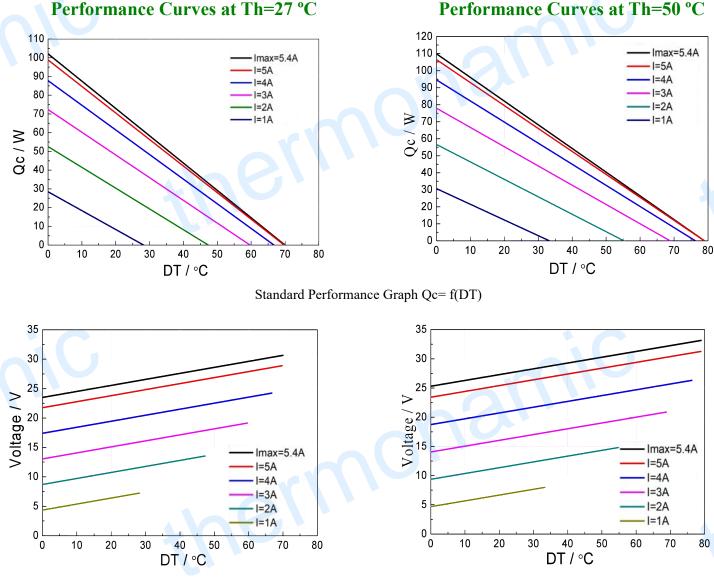
| Suffix | Thickness<br>H (mm) | Flatness/ Parallelism (mm) | Lead wire length(mm)<br>Standard/Optional length |
|--------|---------------------|----------------------------|--|
| TF     | $0:2.75 \pm 0.1$    | 0: 0.05/0.05               | 100±2/Specify                                    |
| TF     | $1:2.75 \pm 0.05$   | 1: 0.03/0.03               | 100±2/Specify                                    |
| TF     | $2{:}2{.}75\pm0.03$ | 2: 0.02/0.02               | 100±2/Specify                                    |

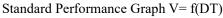
Eg. TF00: Thickness  $2.75 \pm 0.1 \text{ (mm)}$  and Flatness 0.05/0.05 (mm)

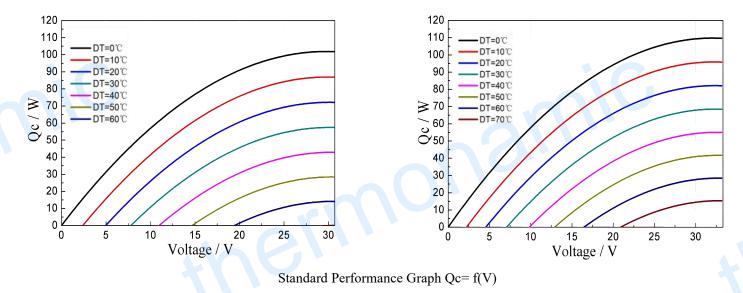
Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

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## TES1-24154ID69OD86

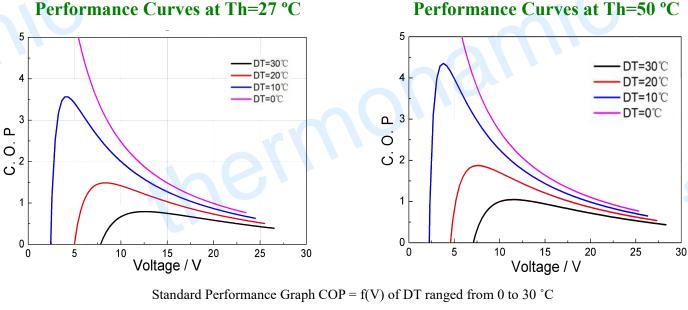


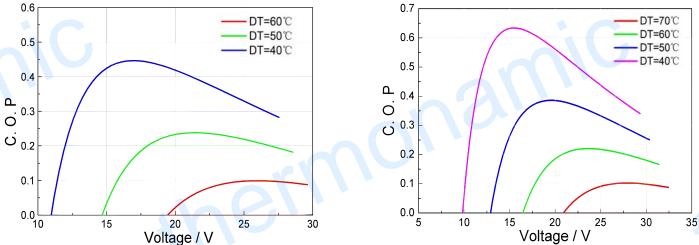




# **Specification of Thermoelectric Module**

## **TES1-24154ID690D86**





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

## **Operation Caution**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.